

ACGI044050-P40-1

C-band matched GaAs Device

Features:

Frequency: 4.4~5GHz 1dB Output Power : $P_{1dB} \ge 40dBm$ PowerGain: Gain $\ge 9dB$ Efficiency: $\eta = 35\%$ (type) Port matching: Zin/Zout=50 Ω

Description:

ACGI044050-P40-1 is an internal matching GaAs device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 4.4~5GHz. This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Maximun Ratings (TC=25 $^{\circ}$ C, Not recommended working under this condition):

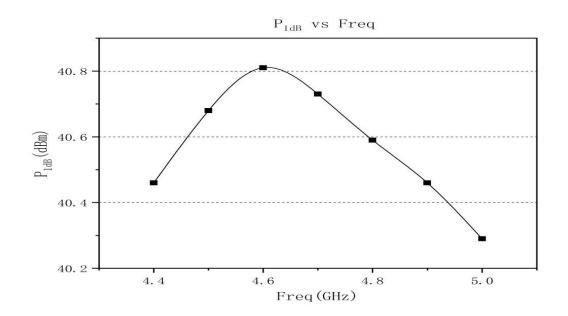
| | Symbol | Value | Unit |
|--------------------------------------|--------|-------------|------|
| Voltage between source and drain | Vds | 11 | V |
| Voltage between gate and source | Vgs | -3 | V |
| Storage Temperature Range | Tstg | -65 to +150 | °C |
| Drain and Source Channel Temperature | Tch | 150 | °C |



Electrical Characteristics:

| | | | Value | | | |
|------------------|------------------|---|-------|-----|------|------|
| | Symbol | ol Test condition | Min | Тур | Max | Unit |
| Drain Current | l _{dsr} | Vds=10V CW. Pin: 31dBm Freq: 4.4~5GHz | - | 2.9 | - | А |
| 1dB output power | P _{1dB} | | 40 | - | - | dBm |
| Gain | G _p | | 9 | - | - | dB |
| Efficiency | η | | - | 35 | - | % |
| Gain Flatness | ΔG | | -0.8 | - | +0.8 | dB |

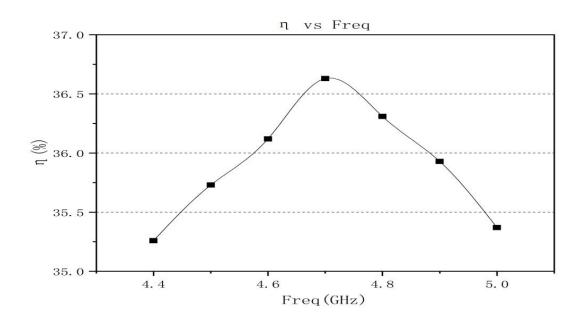
Typical Curve:



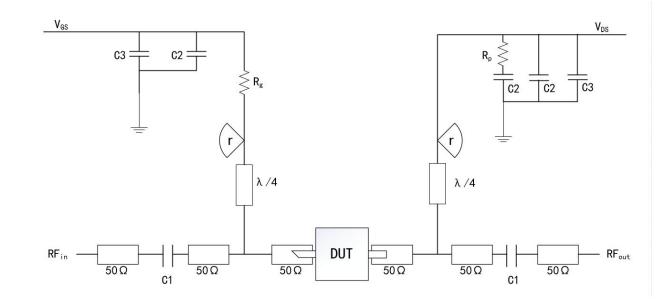
If you need more detailed product information, please contact our marketing personnel or designers. Contact: Peter.Zhang Email: peter.zhang@anserrf.com



Internal Matching GaAs Device



Application Circuit:



DUT: Device to be tested

| C1:4.7pF | Rp:51Ω |
|-----------|------------------------------------|
| C2:1000pF | Rg:15Ω |
| C3:100uF | r(radius)≈5.8mm(Rogers5880, 20mil) |

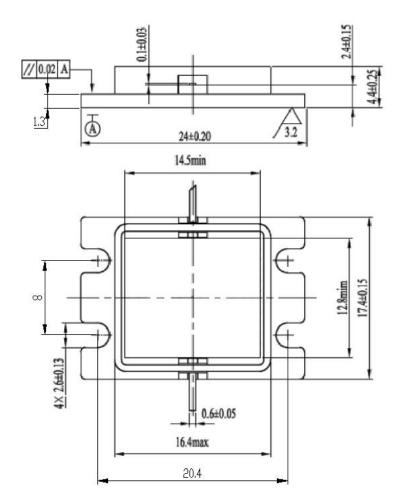
If you need more detailed product information, please contact our marketing personnel or designers. Contact: Peter.Zhang Email: peter.zhang@anserrf.com



ESD Level:



Outline:



Precautions for use:

- Pay attention to drying transportation and storage.
- Pay attention to anti-static during chip use and assembly, and wear grounding anti-static bracelet.
- When powering up, first apply grid power then add leakage.